

AMENDMENTS TO THE CLAIMS

Please amend the Claims as follows. Insertions are shown underlined while deletions are ~~struck through~~.

1 (original): A surface protective film for transparent conductive films protecting a surface of a side opposite to a conductive thin film or a surface on a side of a conductive thin film of the transparent conductive film, wherein an adhesive layer is formed on one side of a base material film, and a rate of thermal shrinkage after being heated at 150°C for 1 hour shows no more than 0.9% in both MD (machine direction) and TD (width direction).

2 (original): The surface protective film for transparent conductive films according to Claim 1, wherein a treatment for removing a residual stress is performed to the base material film.

3 (original): The surface protective film for transparent conductive films according to Claim 1, wherein the base material film is a film including polyethylene terephthalates and/or polyethylene naphthalates.

4 (currently amended): A transparent conductive film with surface protective film, wherein a conductive thin film is formed on one side of a base material film and a hard coat layer or an anti-glare layer is formed on the other surface side, and simultaneously an adhesive layer of the surface protective film for transparent conductive films according to Claims 1-through-3 is attached on a surface of the hard coat layer or the anti-glare layer, or the surface of conductive thin film.

5 (currently amended): A transparent conductive film with surface protective film wherein a conductive thin film is formed on one side of a base material film, and simultaneously an adhesive layer of the surface protective film for transparent conductive films according to Claims 1-through-3 is attached on the other surface side of the base material film or on a surface of the conductive thin film.

6 (currently amended): A method for manufacturing a surface protective film for transparent conductive films according to Claim 2-or-3, wherein after an adhesive is applied to one side of a base material film, a drawing tension of no more than 80 N per width of 1 m of the base material film is applied under conditions of a temperature of 100 through 150°C, and a residence time of 20 through 120 seconds, and thereby a treatment for removing a residual stress and simultaneous drying of the adhesive are performed.

7 (new): A transparent conductive film with surface protective film, wherein a conductive thin film is formed on one side of a base material film and a hard coat layer or an anti-glare layer is formed on the other surface side, and simultaneously an adhesive layer of the surface protective film for transparent conductive films according to Claim 2 is attached on a surface of the hard coat layer or the anti-glare layer, or the surface of conductive thin film.

8 (new): A transparent conductive film with surface protective film, wherein a conductive thin film is formed on one side of a base material film and a hard coat layer or an anti-glare layer is formed on the other surface side, and simultaneously an adhesive layer of the surface protective film for transparent conductive films according to Claim 3 is attached on a surface of the hard coat layer or the anti-glare layer, or the surface of conductive thin film.

9 (new): A transparent conductive film with surface protective film wherein a conductive thin film is formed on one side of a base material film, and simultaneously an adhesive layer of the surface protective film for transparent conductive films according to Claim 2 is attached on the other surface side of the base material film or on a surface of the conductive thin film.

10 (new): A transparent conductive film with surface protective film wherein a conductive thin film is formed on one side of a base material film, and simultaneously an adhesive layer of the surface protective film for transparent conductive films according to Claim 3 is attached on the other surface side of the base material film or on a surface of the conductive thin film.

11 (new): A method for manufacturing a surface protective film for transparent conductive films according to Claim 3, wherein after an adhesive is applied to one side of a base material film, a drawing tension of no more than 80 N per width of 1 m of the base material film is applied under conditions of a temperature of 100 through 150°C, and a residence time of 20 through 120 seconds, and thereby a treatment for removing a residual stress and simultaneous drying of the adhesive are performed.